NOTES:
1. All dimensions are in millimeters.
2. All tolerances ± 0.10mm, unless otherwise noted.
3. Represents the basic land grid pitch.
4. The total number of smaller I/O pads is 17. All 17 I/O's are centered in a fixed row and column matrix at 1.0mm pitch BSC.
6. Tolerance for exposed DAP edge location dimension.
Plastic Packages for Integrated Circuits

SUGGESTED STENCIL OPENING CENTER POSITION

SUGGESTED STENCIL OPENING EDGE POSITION